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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/904,906	07/16/2001	2825	790	740756-2332	6	20	4

CONFIRMATION NO. 4431

22204
NIXON PEABODY, LLP
8180 GREENSBORO DRIVE
SUITE 800
MCLEAN, VA 22102

FILING RECEIPT



OC00000006404360

Date Mailed: 08/09/2001

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Applicant(s)

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Mitsunori ~~Sakama~~ Hiratsuka-shi, JAPAN;
Satoshi Teramoto, Atsugi-shi, JAPAN;
↳ Sakama

Domestic Priority data as claimed by applicant

THIS APPLICATION IS A DIV OF 09/294,338 04/20/1999 PAT 6,268,631
WHICH IS A DIV OF 08/462,773 06/05/1995 PAT 5,929,487
WHICH IS A DIV OF 08/311,275 09/23/1994 PAT 5,674,304

Foreign Applications

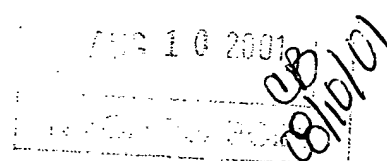
JAPAN 5-279029 10/12/1993

If Required, Foreign Filing License Granted 08/08/2001

Projected Publication Date: 11/15/2001

Non-Publication Request: No

Early Publication Request: No



Title

Glass substrate assembly, semiconductor device and method of heat-treating glass substrate

Preliminary Class

257

Data entry by : LE, THANH-LAN

Team : OIPE

Date: 08/09/2001

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Title 35, United States Code, Section 184
Title 37, Code of Federal Regulations, 5.11 & 5.15**

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PLEASE NOTE the following information about the Filing Receipt:

- The articles such as "a," "an" and "the" are not included as the first words in the title of an application. They are considered to be unnecessary to the understanding of the title.
- The words "new," "improved," "improvements in" or "relating to" are not included as first words in the title of an application because a patent application, by nature, is a new idea or improvement.
- The title may be truncated if it consists of more than 500 characters (letters and spaces combined).
- The docket number allows a maximum of 25 characters.
- If your application was submitted under 37 CFR 1.10, your filing date should be the "date in" found on the Express Mail label. If there is a discrepancy, you should submit a request for a corrected Filing Receipt along with a copy of the Express Mail label showing the "date in."
- The title is recorded in sentence case.

Any corrections that may need to be done to your Filing Receipt should be directed to:

Assistant Commissioner for Patents
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Washington, DC 20231



Attorney Docket No. 0756-2332

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:)	Group Art Unit: 2825
Takeshi FUKADA et al.)	Examiner: L. Malsawma
Serial No. 09/904,906)	CERTIFICATE OF MAILING
Filed: July 16, 2001)	I hereby certify that this correspondence is
For: GLASS SUBSTRATE ASSEMBLY,)	being deposited with the United States Postal
SEMICONDUCTOR DEVICE AND)	Service with sufficient postage as First Class
METHOD OF HEAT-TREATING)	Mail in an envelope addressed to:
GLASS SUBSTRATE)	Commissioner for Patents, P.O. Box 1450,
)	Alexandria, VA 22313-1450, on
)	3.31.2004
)	<u>Adelle M. Stamper</u>

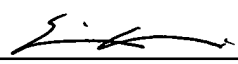
SUBMISSION OF CORRECTED APPLICATION DATA SHEET
AND REQUEST FOR CORRECTED OFFICIAL FILING RECEIPT

Honorable Commissioner of Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Inventor Mitsunori Sakama's name is misspelled on the Application Data Sheet originally filed in the subject application. As a result of this error, Mr. Sakama's name is also misspelled on the Official Filing Receipt (copy enclosed). Applicant is hereby notifying the U.S.P.T.O. of this error and requests correction by submission of the enclosed Supplemental Application Data Sheet. In view of the above, it is requested that a Corrected Filing Receipt be issued. The fee in the amount of \$25.00 is enclosed.

Respectfully submitted,


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Application Data Sheet

Application Information

Application number::

Filing Date::

Application Type::

Regular

Subject Matter::

Utility

Title ::

GLASS SUBSTRATE
ASSEMBLY,
SEMICONDUCTOR DEVICE
AND METHOD OF HEAT-
TREATING GLASS
SUBSTRATE

Attorney Docket Number::

0756-2332

Total Drawing Sheets::

6

Small Entity?::

No

Applicant Information

Applicant Authority Type::

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Representative Information

Representative Customer Number:: 31780

Domestic Priority Information

Application ::	Continuity Type::	Parent Application::	Parent Filing Date::
This Application	Divisional	09/294,338	04/20/1999
09/294,338	Divisional	08/462,773	06/05/1995
08/462,773	Divisional	08/311,275	09/23/1994

Foreign Priority Information

Country::	Application number::	Filing Date::	Priority Claimed::
Japan	05-279029	10/12/1993	Yes

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